



国芯展 · 上海国际嵌入式会议

2026. 10. 14 - 16 国家会展中心 5.2 馆

IC ECOSYSTEM SHOW · embedded world China Conference

Hall 5.2, National Exhibition & Convention Center, Shanghai, China

分论坛: 嵌入式技术会议

Track 1 Embedded Technology & Applications

分论坛: 先进封装与异构集成驱动嵌入式系统创新研讨会

Track 2 Symposium on Advanced Packaging and Heterogeneous Integration Driving Embedded System Innovation

分论坛: Zephyr 开源实时操作系统

Track 3 Zephyr Open Source Real-Time Operating System

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上海国际嵌入式会议将于 2026 年 10 月 14 - 16 日在国家会展中心（上海）举办。此次会议将由三个版块组成：嵌入式技术会议、先进封装与异构集成驱动嵌入式系统创新研讨会、Zephyr 开源实时操作系统。

三个版块均采用论文征集的形式，对每一位在嵌入式系统产业有自己观点与见解的人士提供平等的参与机会，无论是精专深度的学术探讨，或是日常研发应用的案例分析，均可通过征集平台被专家顾问委员会所看到，并有机会作为演讲人与参会听众交流。

征文入选规则

入选原则 - 真实、原创、具有创新视角，投稿人亲身实例为佳。

国内外专业领域与权威机构的专家、教授、企业高层，将组成顾问委员会，为会议品质的提升、分享内容的甄选，以及大会议程的安排，提出专业的指导建议。

大会安排

摘要提交截止	2026.9.22
作者通知	2026.10.1
议程公布	2026.10.6
演讲材料提交	2026.10.10
大会开幕	2026.10.14-16

The embedded world China Conference will take place from October 14 to 16, 2026 at the National Exhibition and Convention Center (Shanghai).

The main topics of this year's conference are

- Embedded Technology & Applications
- Symposium on Advanced Packaging and Heterogeneous Integration Driving Embedded System Innovation
- Zephyr Open Source Real-Time Operating System

Interested speakers for all three tracks are invited to submit their proposals to contribute to the 4th edition of the conference with a technical presentation or paper. The embedded world China Conference 2026 calls for future-oriented technologies and solutions, best practices, new ideas and smart concepts for efficient development and lifecycle processes. The presentations will be used to initiate discussions and help other engineers and managers to benefit from shared experiences.

Experts with insight into the embedded systems industry is given an equal opportunity to participate, whether through in-depth academic discussions, technological show cases or best practice studies from research and development.

Acceptance Criteria

Papers will be selected based on the following criteria:

- novelty
- technological soundness
- technological significance
- experience of the speaker

Important Deadlines

• Abstract Submission	22. Sep. 2026
• Notification of Authors	1. Oct. 2026
• Agenda Released	6. Oct. 2026
• Submission of Presentations	10. Oct. 2026
• embedded world China Conference	14-16. Oct. 2026

The selection will be made by a programme committee. The members of the programme committee are independent senior engineers and researchers with excellent scientific and business experience.

分论坛：嵌入式技术会议

Track 1 Embedded Technology & Applications

为业界呈现满载着前沿信息、丰富应用与深刻案例分享的技术盛宴。来自中国及全球各地的杰出演讲嘉宾齐聚一堂，通过他们的精彩演讲，与会者将得以一窥行业最前沿的技术风貌，洞悉未来发展趋势。

[点击链接投稿](#)

Embedded Technology & Applications offers the industry with a technology feast full of cutting-edge information, rich applications and insightful case sharing. Gathering eminent speakers from China and around the world, through their wonderful speeches, participants will be able to get a glimpse of the industry's most cutting-edge technology and insight into the future development trend.

[Click on the link to submit a paper](#)

论文征集范围

1. 物联网——平台与应用

- 1.1 物联网架构与管理
- 1.2 应用协议和配置文件： OPC UA、MQTT、LWM2M、CANopen、Matter...
- 1.3 物联网软件平台
- 1.4 数据管理、隐私与分析
- 1.5 物联网应用案例研究

2. 连接解决方案

- 2.1 有线： CAN、以太网、TSN...
- 2.2 无线 LPWAN、NB IoT、5G/6G、蓝牙 ...
- 2.3 网络架构与管理、网关
- 2.4 连接性应用案例研究

3. 嵌入式操作系统

- 3.1 实时操作系统： 开源与闭源、安全、多核 ...
- 3.2 基于 Linux 的 嵌入式 Linux、Android、ROS
- 3.3 云集成与服务
- 3.4 虚拟化与 Dockers
- 3.5 应用案例研究： 现场更新、OTA...

4. 安全与保障

- 4.1 功能安全与安全架构
- 4.2 功能安全与安保标准、CRA
- 4.3 密码学与可信计算
- 4.4 长期安全与后量子密码学
- 4.5 黑客攻击
- 4.6 安全可靠系统的鉴定
- 4.7 安全可靠系统的应用案例研究

5. 板级硬件工程

- 5.1 微控制器
- 5.2 存储器
- 5.3 传感器和执行器
- 5.4 电路板与封装： 高性能、射频与天线
- 5.5 设计、印刷与柔性电子 ...
- 5.6 能源与电源管理
- 5.7 电源、无线、以太网供电

6. 系统与软件工程

- 6.1 流程与方法： 敏捷、DevOps、MLOps、MBSE...
- 6.2 用户界面设计与设计思维
- 6.3 人工智能辅助工程
- 6.4 编程语言： C、C++、Rust...
- 6.5 编码标准与静态分析： MISRA ...
- 6.6 质量、测试与验证、调试
- 6.7 开放源代码

7. 嵌入式视觉

- 7.1 硬件组件与系统集成
- 7.2 软件工具（包括人工智能）和工具链
- 7.3 标准化（如相机接口）
- 7.4 嵌入式雷达、嵌入式激光雷达
- 7.5 嵌入式视觉应用案例研究

8. 边缘人工智能

- 8.1 传感器融合与集成
- 8.2 嵌入式 ML 与 AI 算法
- 8.3 支持人工智能的硬件
- 8.4 可解释与可预测的人工智能
- 8.5 人工智能系统的鉴定
- 8.6 嵌入式 ML/AI 的应用案例研究

9. 片上系统 (SoC) 设计

- 9.1 数字电路与系统： 芯片、FPGA、ASIC...
- 9.2 模拟、射频和混合信号电路与系统
- 9.3 IP 和集成电路级开放式硬件： RISC-V、MIPS....
- 9.4 EDA 工具
- 9.5 代工技术
- 9.6 应用案例研究

10. 绿色和可持续工程

- 10.1 法律要求和标准
- 10.2 工程道德
- 10.3 可持续发展与循环经济工程学
- 10.4 生命周期工程学

11. 应用案例

- 11.1 工业、自动化、设施管理
- 11.2 关键基础设施： 能源、水、通信
- 11.3 交通运输： 汽车、航空电子、铁路
- 11.4 安全与国防
- 11.5 生命科学： 医疗、健康、福利
- 11.6 环境、农业、海洋
- 11.7 物流与零售
- 11.8 其他

Topics of interest include

1. Internet of Things – Platforms & Applications

- 1.1 IoT Architectures & Management
- 1.2 Application Protocols & Profiles: OPC UA, MQTT, LWM2M, CANopen, Matter...
- 1.3 Software Platforms for IoT
- 1.4 Data Management, Privacy & Analytics
- 1.5 Application Case Studies for IoT

2. Connectivity Solutions

- 2.1 Wired: CAN, Ethernet, TSN, ...
- 2.2 Wireless: LPWAN, NB IoT, 5G/6G, Bluetooth, ...
- 2.3 Network Architectures & Management, Gateways
- 2.4 Application Case Studies for Connectivity

3. Embedded OS

- 3.1 RTOS: Open & Closed Source, Safety, Multicore, ...
- 3.2 Linux-based: Embedded Linux, Android, ROS
- 3.3 Cloud Integration & Services
- 3.4 Virtualization & Dockers
- 3.5 Application Case Studies: Field Updates, OTA, ...

4. Safety & Security

- 4.1 Functional Safety & Security Architectures
- 4.2 Functional Safety & Security Standards, CRA
- 4.3 Cryptography & Trusted Computing
- 4.4 Long-Term Security & Post-Quantum Cryptography
- 4.5 Hacking
- 4.6 Qualification of Safe and Secure Systems
- 4.7 Application Case Studies for Safe and Secure Systems

5. Board Level Hardware Engineering

- 5.1 IMicrocontrollers
- 5.2 Memory
- 5.3 Sensors & Actuators
- 5.4 PCB & Packaging: High Performance, RF & Antenna Design, Printed & Flexible Electronics, ...
- 5.5 Energy & Power Management
- 5.6 Power Supply: Wireless, Power over Ethernet, ...

6. Systems & Software Engineering

- 6.1 Processes & Methods: Agile, DevOps, MLOps, MBSE, ...
- 6.2 UI Design & Design Thinking
- 6.3 AI Assisted Engineering
- 6.4 Programming Languages: C, C++, Rust, ...
- 6.5 Coding Standards & Static Analysis: MISRA, ...
- 6.6 Quality, Test & Verification, Debug
- 6.7 Open Source

7. Embedded Vision

- 7.1 HW Components & System Integration
- 7.2 Software Tools (incl. AI) & Toolchains
- 7.3 Standardisation (e.g. Camera Interfaces)
- 7.4 Embedded Radar, Embedded Lidar
- 7.5 Application Case Studies for Embedded Vision

8. Edge AI

- 8.1 Sensor Fusion & Integration
- 8.2 Algorithms for Embedded ML & AI
- 8.3 Hardware Support for ML & AI
- 8.4 Explainable & Predictable AI
- 8.5 Qualification of AI Systems
- 8.6 Application Case Studies for Embedded ML/AI

9. System-on-Chip (SoC) Design

- 9.1 Digital Circuits & Systems: Chipllets, FPGA, ASIC, ...
- 9.2 Analog, RF & Mixed-Signal Circuits & Systems
- 9.3 Open HW at IP- and IC-Level: RISC-V, MIPS, ...
- 9.4 EDA Tools
- 9.5 Foundry Technologies
- 9.6 Application Case Studies

10. Green and Sustainable Engineering

- 10.1 Legal Requirements and Standards
- 10.2 Engineering Ethics
- 10.3 Engineering for Sustainability & Circular Economy
- 10.4 Lifecycle Engineering

11. Application Use Cases

- 11.1 Industrial, Automation, Facility Management
- 11.2 Critical Infrastructure: Energy, Water, Communication
- 11.3 Transport: Automotive, Avionics, Railway
- 11.4 Security & Defence
- 11.5 Life Sciences: Medical, Health, Wellbeing
- 11.6 Environmental, Agriculture, Marine
- 11.7 Logistics & Retail
- 11.8 Others

分论坛：先进封装与异构集成驱动嵌入式系统创新研讨会

Track 2 Symposium on Advanced Packaging and Heterogeneous Integration Driving Embedded System Innovation

本次研讨会旨在打通“制造工艺—封装集成—嵌入式应用”的技术闭环，聚焦面向工业级嵌入式 AI 的高性能芯片制造、基于 RISC-V 的定制化算力加速、系统级封装 (SiP) 与 2.5D / 3D 异构集成技术，以及机器视觉在先进封装检测与嵌入式系统中的应用实践等关键议题。通过邀请芯片设计、封测、EDA 工具、系统集成与整机应用等产业链各环节的领先企业，共同探讨如何以应用需求驱动半导体技术创新，推动从芯片到工业终端的高效落地。研讨会不仅是对 embedded world “由工程师，为工程师”理念的延续与深化，更是国芯展“从芯片到场景”全链条价值的最佳诠释——让技术回归工业应用的主场，让创新在真实需求中生根。

[点击链接投稿](#)

The symposium is designed to bridge the closed technology loop covering manufacturing processes, packaging integration and embedded applications. It will focus on core themes including high-performance chip fabrication for industrial-grade embedded AI, customized computing acceleration based on RISC-V, System-in-Package (SiP) and 2.5D/3D heterogeneous integration technologies, as well as real-world deployments of machine vision for advanced packaging inspection and embedded systems. We will gather leading enterprises spanning chip design, packaging & testing, EDA tools, system integration and complete machine manufacturing to discuss how application demands drive semiconductor technological innovation and accelerate the efficient industrial implementation of chips in end devices.

[Click on the link to submit a paper](#)

重点聚焦

- 面向嵌入式 AI 的高性能芯片制造工艺
- RISC-V 嵌入式 AI 解决方案
- 芯片嵌入式封装技术在 AI 与汽车电子领域的应用
- 2.5D / 3D EDA 与 STCO 协同设计
- SiP 技术驱动嵌入式终端微小化与模组化
- 嵌入式机器视觉系统的芯片级解决方案
- 高性能嵌入式系统在工业视觉与 AI 质检中的设计挑战与应用
- 先进封装的视觉检测挑战与 AI 解决方案 / 先进封装 AOI 检测
- 车规级嵌入式芯片的封装可靠性与系统集成
- 嵌入式视觉在具身智能、智能终端中的应用

Key focus

- High-performance Chip Fabrication Processes for Embedded AI
- RISC-V-Based Embedded AI Solutions
- Packaging Technology for Embedded Chips: Applications in AI and Automotive Electronics
- 2.5D & 3D EDA and STCO Co-Design Methodology
- SiP Technologies Enabling Miniaturization and Modularization of Embedded End Devices
- Chip-Level Solutions for Embedded Machine Vision Systems
- High-Performance Embedded Systems: Design Challenges & Deployments in Industrial Vision and AI Quality Inspection
- Vision Inspection Challenges and AI-Driven AOI Solutions for Advanced Packaging
- Packaging Reliability and System Integration of Automotive-Grade Embedded Chips
- Embedded Vision Applications in Embodied Intelligence and Smart Edge Terminals

分论坛：Zephyr开源实时操作系统

Track 3 Zephyr Open Source Real-Time Operating System

ewCN Conference 将与 Zephyr® 合作，进行论文征集→[点击链接投稿](#)。

Zephyr 将在 ewCN 2026 现场呈现 / 概述以下方向议题：

1. 内核与系统优化：多核异构调度、确定性实时增强、RISC-V / ARM 多架构适配、低功耗剪裁、内存资源优化……
2. 工业互联协议：CANopen、EtherCAT、TSN、PROFINET、OPC UA、MQTT、LwM2M、Modbus、工业边缘网关……
3. 功能安全与信息安全：IEC 61508 认证、SIL 等级适配、安全启动、可信执行、OTA 全生命周期管理、工业网络防护……
4. 工业边缘 AI 与感知：TinyML 轻量模型、多传感器融合、工业视觉端侧推理、设备预测性维护、边缘数据预处理……
5. 工具链与工程化实践：开发调试框架、DevOps/CI/CD 落地、测试验证体系、SBOM 管理、虚拟化与数字孪生对接……
6. 智能制造场景落地：智能工厂传感节点、工业运动控制、机器人嵌入式端、新能源设备、绿色低碳能效优化……
7. 国产化与生态共建：国产芯片 / MCU 适配、工业级开源组件、国产化工业软件集成、LTS 版本长期运维……
8. 工业应用案例研究：离散制造、流程工业、智慧能源、智能仓储、轨道交通、环保监测……

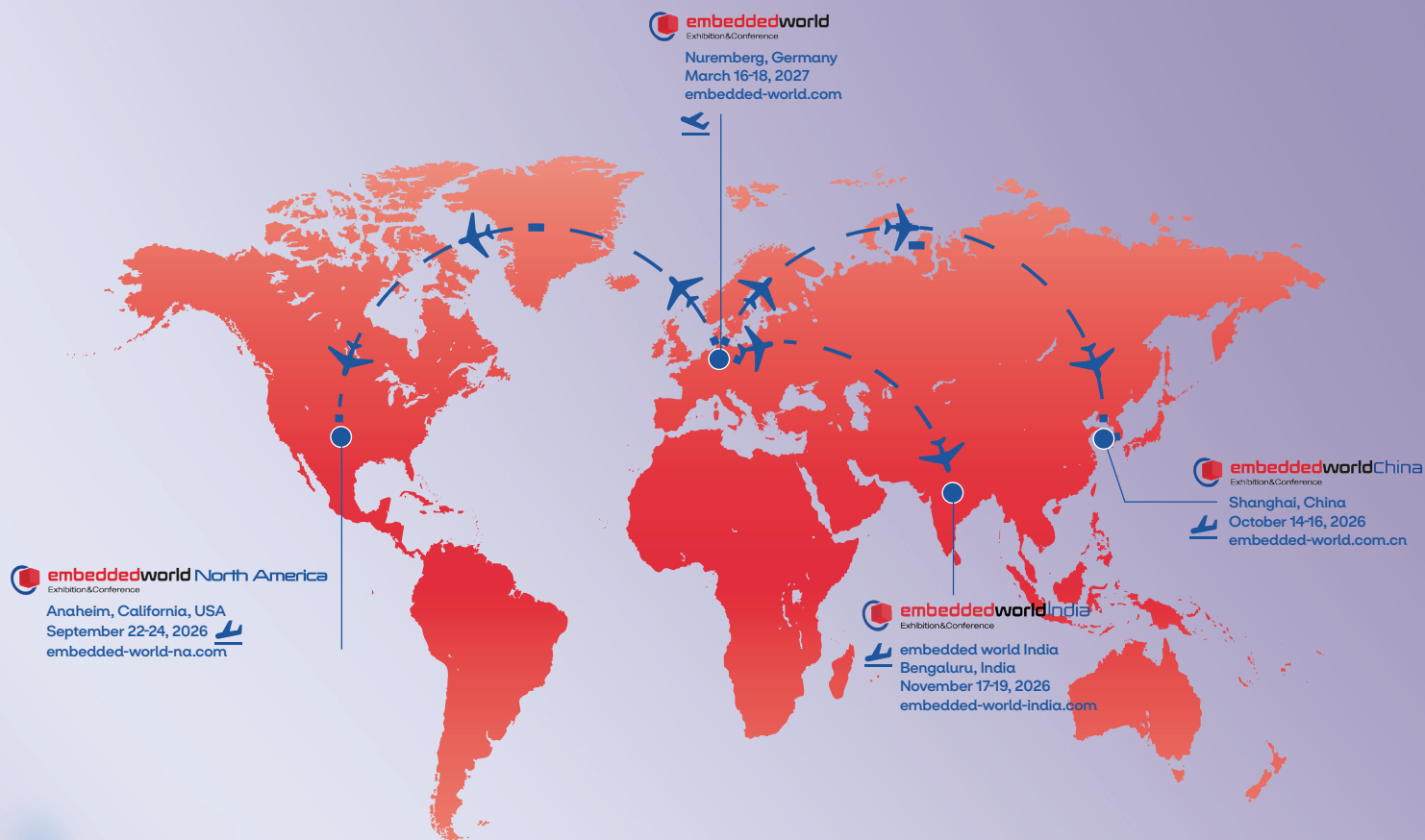
ewCN Conference will be working closely with Zephyr® on a call for papers.

[Click on the link to submit a paper](#)

The special Zephyr session topics shall give an overview of new technology trends. The special topics of the Zephyr session will include:

- Kernel & System Optimization: Multi-core heterogeneous scheduling, deterministic real-time enhancement, multi-architecture adaptation for RISC-V/ARM, low-power tailoring, memory resource optimization...
- Industrial Interconnection Protocols & Gateways: CANopen, EtherCAT, TSN, PROFINET, OPC UA, MQTT, LwM2M, Modbus, industrial edge gateways...
- Functional Safety & Cybersecurity: IEC 61508 functional safety certification, SIL level compliance, secure boot, trusted execution, OTA full lifecycle management, industrial network protection...
- Industrial Edge AI & Sensing Fusion: TinyML lightweight models, multi-sensor fusion, on-device inference for industrial vision, predictive equipment maintenance, edge data preprocessing...
- Toolchain & Engineering Practice: Development and debugging framework, DevOps / CI / CD implementation, testing and verification system, SBOM management, virtualization and digital twin integration...
- Smart Manufacturing Scenario Implementation: Smart factory sensor nodes, industrial motion control, embedded systems for robotics, new energy equipment control, green & low-carbon energy efficiency optimization...
- Localization & Ecosystem Co-construction: Domestic chip / MCU adaptation, industrial-grade open source components, localized industrial software integration, long-term maintenance of LTS releases...
- Industrial Application Case Studies: Discrete manufacturing, process industry, smart energy, intelligent warehousing, rail transit, environmental monitoring...

期待与您十月再相聚！ See you in October !



联系我们 Contact

分论坛：嵌入式技术会议

Track 1 Embedded Technology & Applications

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分论坛：Zephyr 开源实时操作系统

Track 3 Zephyr Open Source Real-Time Operating System

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分论坛：先进封装与异构集成驱动嵌入式系统创新研讨会

Track 2 Symposium on Advanced Packaging and Heterogeneous Integration Driving Embedded System Innovation

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